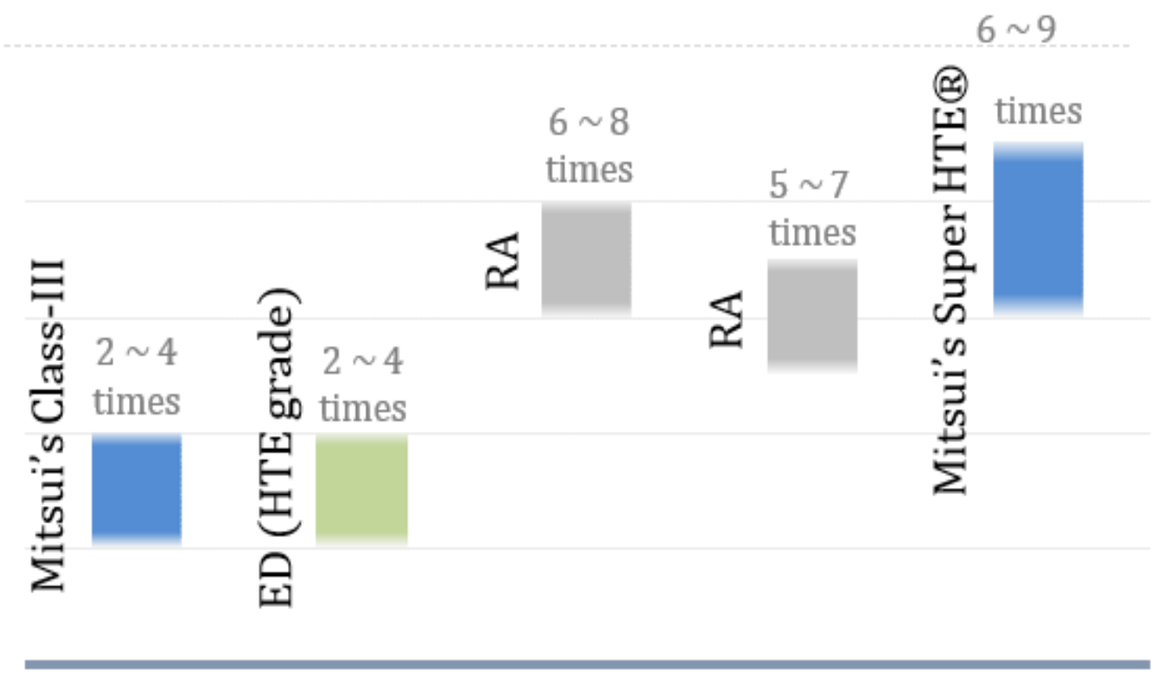
Super HTE®系列

兩層/三層軟性基板適用的低溫退火電解銅箔

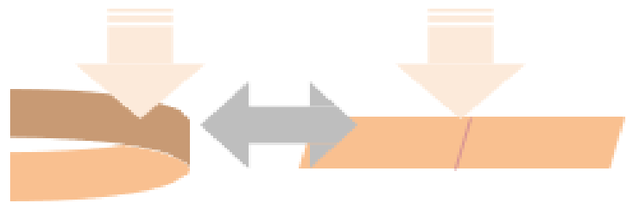
Low temperature annealing ED Copper Foil for 2Layer/3Layer FCCL

S-HTE Series : 3EC-M2S-HTE® & 3EC-M3S-HTE®

死折繞曲特性 Dead-fold flexibility

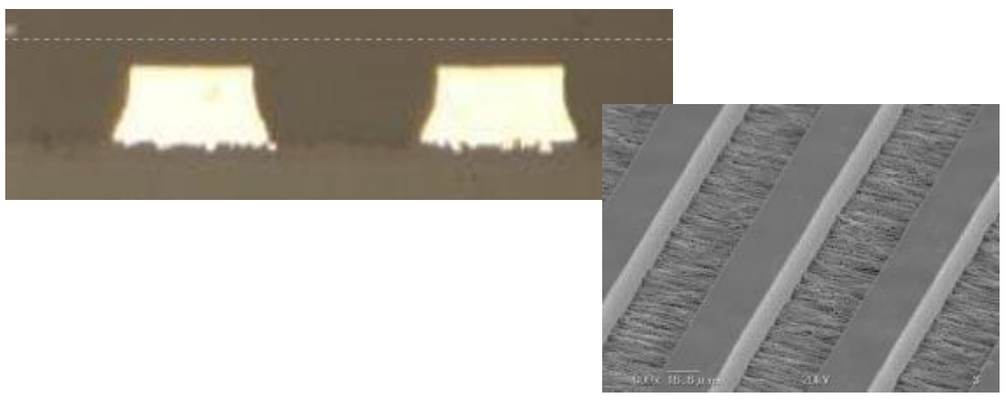


- 等同於壓延銅箔的死折繞曲特性
  Equivalent dead-fold flexibility performance to RA foil
- 比一般HTE電解銅箔有更優異的繞折特性
  Advantageous flexibility to conventional HTE grade ED foil



條件:
- 兩層雙面板(12μm/1mil/12μm)
- 銅箔寬度1cm
- 下壓力10kgf

細線路的蝕刻特性 Etching performance for fine line



- L/S = 45/35μm的線路成形可達到3.5左右的蝕刻因子
  (線 高 20μm, 銅 箔 厚 度 12μm)
- Etching factor marked 3.5 around when forming L/S=45/35μm circuitry on 20μm thick Cu
  (=12μm foil & plating)

** 9um 3EC-M2S-HTE able to perform excellent Etching Performance for Fine Line Patterning.

** 9um 3EC-M2S-HTE, 對微細線路成形特別顯得優越

Super HTE Series	Surface Roughness Lam. Side [μm]	Cross Section Image	Thickness [μm]
3EC-M2S-HTE®	Rz 1.8		9 μm
3EC-M3S-HTE®	Rz 2.5		12 μm / 18 μm / 35 μm

* Mass Production in Mitsui Copper Foil Malaysia plant.

銅箔具優越特性，適用於高端軟板應用

Excellent Copper Foil characteristic for Advance Flexible Board application.

◎ 三井特產之超高延展性銅箔, 擁有優越的柔軟特性及繞折表現。
◎ 翻轉銅瘤化處理之超低粗度, 對微細線路成形特別顯得優越。
◎ 超低粗度特性對高頻高速運用上, 具優良訊號傳輸及低損耗的功能。
◎ 具備充足及全面可靠的產能, 確保滿足客户需求。

◎ Mitsui proprietary Super-HTE copper foil with excellent flexural characteristic and bending performance.
◎ Reversed-Treated copper foil with lower profile on bonding surface which has excellent advantages on fine circuit.
◎ Excellent performance in Signal lost for High Speed High frequency FPCB application.
◎ Good track record of reliable and advance production capability to fulfil customers' volume requirement.

三井金属